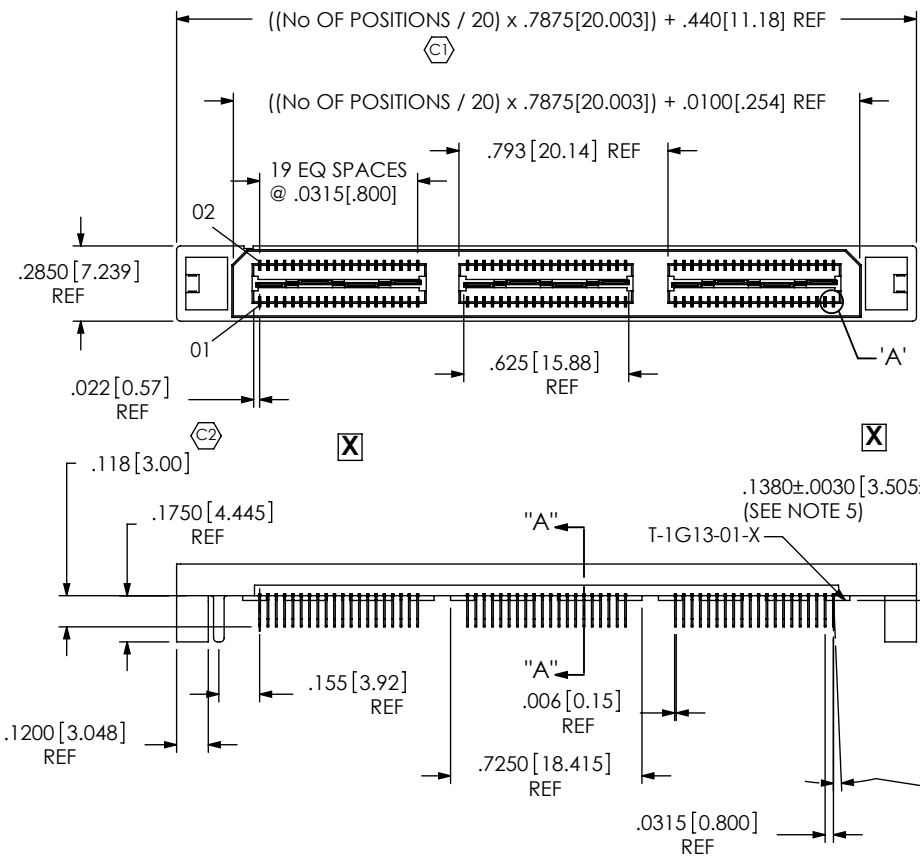


DO NOT SCALE FROM THIS PRINT



QSE-XXX-01-X-D-EMX-XX

No OF POSITIONS
 -020, -040, -060
 ** -080, ** -100
 (PER ROW)

LEAD STYLE
 -01: .1380 [3.505]

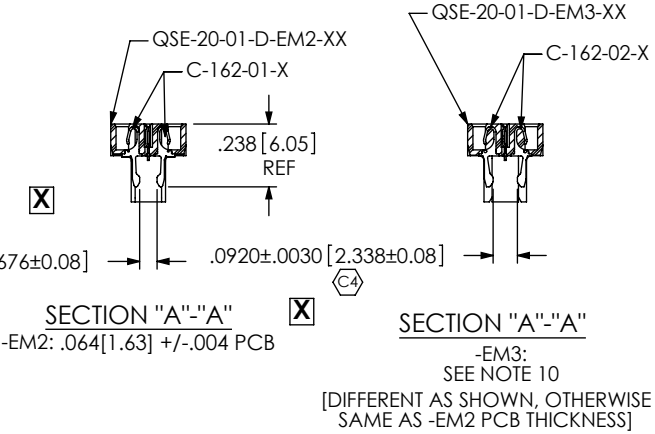
PLATING SPECIFICATION
 -F: FLASH SELECTIVE GOLD WITH MATTE TIN TAILS (USE C-162-XX-F & T-1G13-01-F) (SEE NOTE 6)
 -L: LIGHT SELECTIVE GOLD WITH MATTE TIN TAILS (USE C-162-XX-L & T-1G13-01-L)
 -H: HEAVY GOLD (USE C-162-XX-H & T-1G13-01-G)
 -TL: TIN/LEAD

OPTION
 * -GP: GUIDE POST (60 POS MAX) (SEE FIG. 2, SEE SHEET 2)
 -TY: TRAY PACKAGING
 * EM3-GP = NOT TOOLED

EDGE MOUNT THICKNESS
 -EM2: .064[1.63] +/- .004 PCB (USE QSE-20-01-D-EM2-XX & C-162-01-X)
-EM3: (USE QSE-20-01-D-EM3-XX & C-162-02-X) SEE NOTE 10

ROW SPECIFICATION
 -D: DOUBLE (USE QSE-20-01-D-EMX-XX)

No OF BANKS



* = SEE NOTE 10
 ** = SEE NOTE 11

- NOTES:
1. ⓧ REPRESENTS A CRITICAL DIMENSION.
 2. CONTACT RETENTION: 6 OZ MIN.
 3. GROUND PLANE RETENTION: 8 OZ MIN.
 4. PARTS ARE MOLD TO POSITION.
 5. MAX VARIANCE OF .002[.05].
 6. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING.
 7. NOTE DELETED.
 8. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
 9. SEE WWW.SAMTEC.COM/PROCESSING/EDGEMOUNT_TECTALK/INDEX.HTM FOR INFORMATION ON PROCESSING EDGEMOUNT PARTS TO BOARDS.
 10. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
 11. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP.

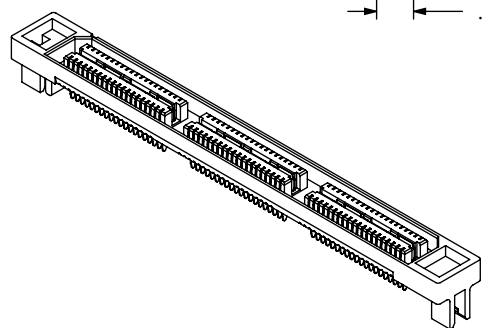


TABLE 1		
No OF POSITIONS	GND PLANE COPLANARITY	ASSEMBLY BOW
-020 THRU -060	.004 [.10]	.004 [.10]
-080 THRU -100	.005 [1.27]	.006 [.15]

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES. TOLERANCES ARE:

DECIMALS ANGLES
 .XX: ±.01 [.3]
 .XXX: ±.005 [.13]
 .XXXX: ±.0020 [.051]

PROPRIETARY NOTE
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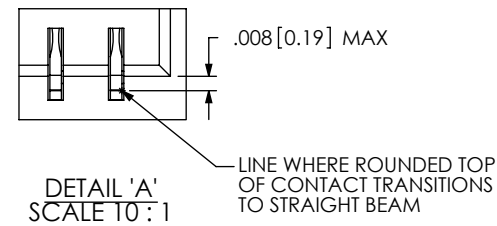
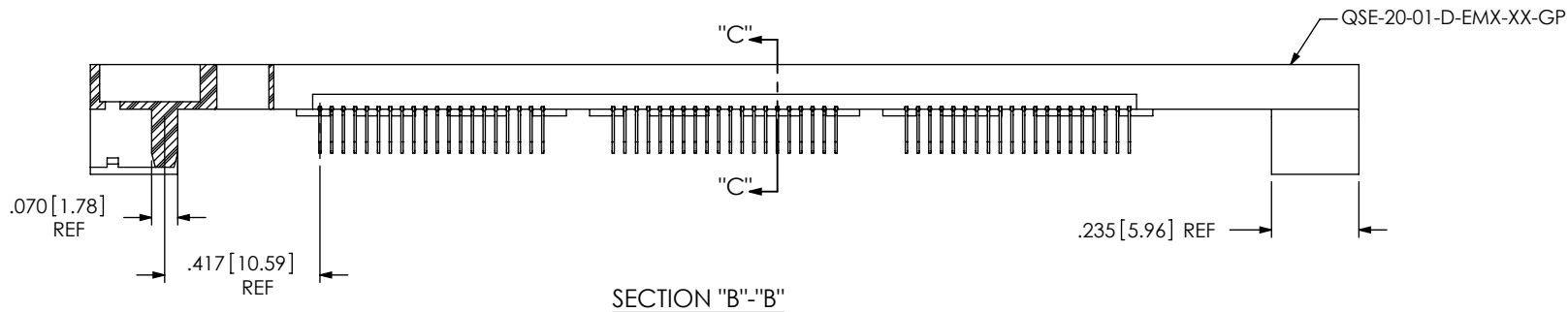
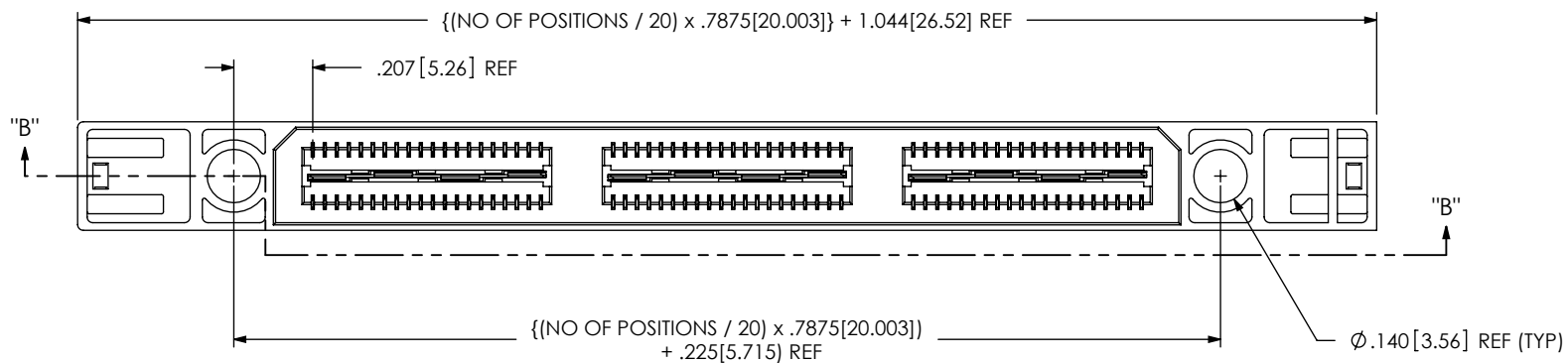


520 PARK EAST BLVD, NEW ALBANY, IN 47150
 PHONE: 812-944-6733 FAX: 812-948-5047
 e-Mail: info@SAMTEC.com code: 55322

MATERIAL: DO NOT SCALE DRAWING	SHEET SCALE: 1:375:	DESCRIPTION: .8mm EDGE MOUNT HS SOCKET ASSEMBLY
INSULATOR: LCP, -EM2 COLOR: BLACK -EM3 COLOR: NATURAL	CONTACT & GROUND PLANE: PHOS BRONZE	DWG. NO. QSE-XXX-01-X-D-EMX-XX
BY: DEAN P 5/24/2000		SHEET 1 OF 2

FIG. 2

-GP: GUIDE POST
 (DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG.1)
 (60 POSITION MAX)
 (ONLY AVAILABLE WITH -EM2 OPTION)



CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE		
ASSEMBLY OPERATION	START-UP INSPECTION INSPECT CODE A	IN-PROCESS INSPECTION INSPECT CODE B
FILL T-1G13-01-X		C6
FILL C-162-XX-X	C1, C4	C2, C4*, C5**

* = APPLICABLE FOR -EM3 ONLY
 ** = APPLICABLE FOR -EM2 ONLY



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	520 PARK EAST BLVD, NEW ALBANY, IN 47150 PHONE: 812-944-6733 FAX: 812-948-5047 e-Mail: info@SAMTEC.com code: 55322	
DESCRIPTION: .8mm EDGE MOUNT HS SOCKET ASSEMBLY		
DWG. NO. QSE-XXX-01-X-D-EMX-XX		
BY: DEAN P	5/24/2000	SHEET 2 OF 2